



BSI Standards Publication

## Space engineering — Thermal design handbook

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Part 10: Phase — Change Capacitor

## National foreword

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## European Foreword

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This document (CEN/CLC/TR 17603-31-10:2021) has been prepared by Technical Committee CEN/CLC/JTC 5 "Space", the secretariat of which is held by DIN.

It is highlighted that this technical report does not contain any requirement but only collection of data or descriptions and guidelines about how to organize and perform the work in support of EN 17603-31.

This Technical report (TR 17603-31-10:2021) originates from ECSS-E-HB-31-01 Part 10 A.

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This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and has therefore precedence over any TR covering the same scope but with a wider domain of applicability (e.g.: aerospace).

# 1 Scope

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Solid-liquid phase-change materials (PCM) are a favoured approach to spacecraft passive thermal control for incident orbital heat fluxes or when there are wide fluctuations in onboard equipment.

The PCM thermal control system consists of a container which is filled with a substance capable of undergoing a phase-change. When there is an the increase in surface temperature of spacecraft the PCM absorbs the excess heat by melting. If there is a temperature decrease, then the PCM can provide heat by solidifying.

Many types of PCM systems are used in spacecrafts for different types of thermal transfer control.

Characteristics and performance of phase control materials are described in this Part. Existing PCM systems are also described.

The Thermal design handbook is published in 16 Parts

TR 17603-31-01	Thermal design handbook – Part 1: View factors
TR 17603-31-02	Thermal design handbook – Part 2: Holes, Grooves and Cavities
TR 17603-31-03	Thermal design handbook – Part 3: Spacecraft Surface Temperature
TR 17603-31-04	Thermal design handbook – Part 4: Conductive Heat Transfer
TR 17603-31-05	Thermal design handbook – Part 5: Structural Materials: Metallic and Composite
TR 17603-31-06	Thermal design handbook – Part 6: Thermal Control Surfaces
TR 17603-31-07	Thermal design handbook – Part 7: Insulations
TR 17603-31-08	Thermal design handbook – Part 8: Heat Pipes
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